# **APPROVAL SHEET**

# CrossAir<sup>™</sup> SMD antenna series RoHS Compliance

Model: CA-C01

2.4 GHz ISM band antenna

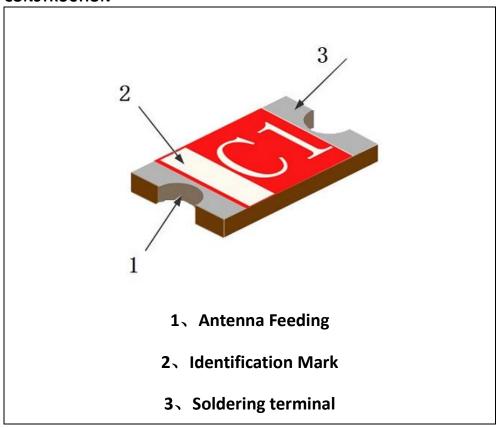
#### **FEATURES**

- 1. Surface Mounted Devices with a small dimension of 3.2  $\times$  1.6  $\times$  0.4 mm $^3$  meet miniaturization trend.
- 2. Low power loss and high antenna efficiency.
- 3. High stability in Temperature and Humidity Change.

#### **APPLICATIONS**

- 1. 2.4GHz ISM band RF applications
- 2. Bluetooth, Wireless, HomeRF

# **CONSTRUCTION**



#### **DIMENSIONS**

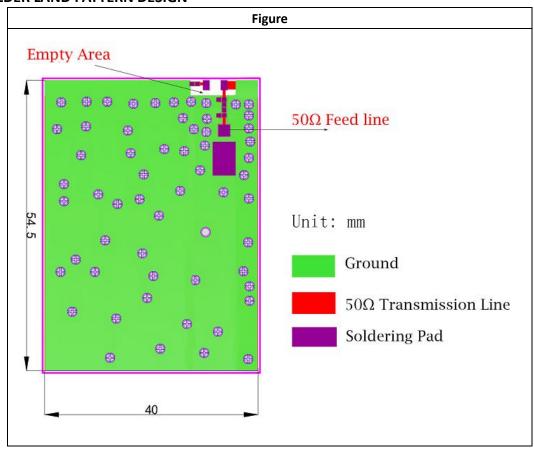
Figure	Symbol	Dimension(mm)	
a=0.6 (mm)  W= 1.6 (mm)  L= 3.2 (mm)  T= 0.4 (mm)	L	<b>3.2</b> ±0.1	
	w	<b>1.6</b> ±0.1	
	Т	<b>0.4</b> ±0.05	
	a	<b>0.6</b> ±0.1	

#### **ELECTRICAL CHARACTERISTICS**

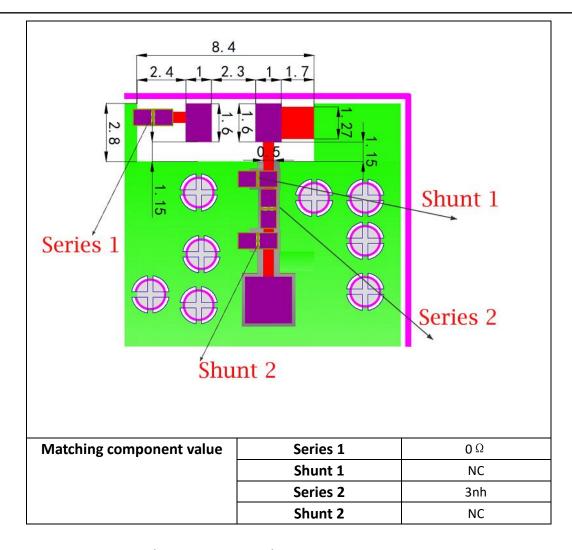
Model: CAC01	Specification	
Working Frequency Range	<b>2450</b> ±50MHz	
Band Width	>100MHz	
Impedance	50 Ω	
Gain(dBi)	0.2	
VSWR	<2	
Operation Temperature	-40℃~+85℃	
Power Capacity	3W	

The working frequency need be adjusted to 2.45GHz with matching circuit.

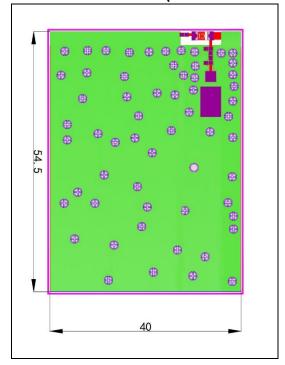
# **SOLDER LAND PATTERN DESIGN**

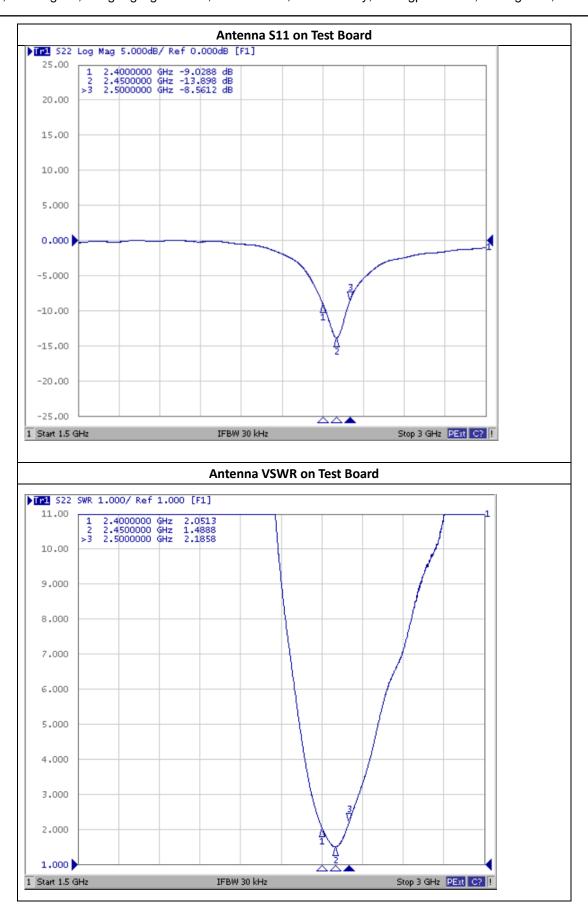


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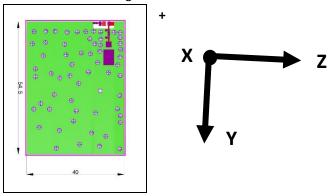
# Antenna on Test Board (Thickness 1.0mm)



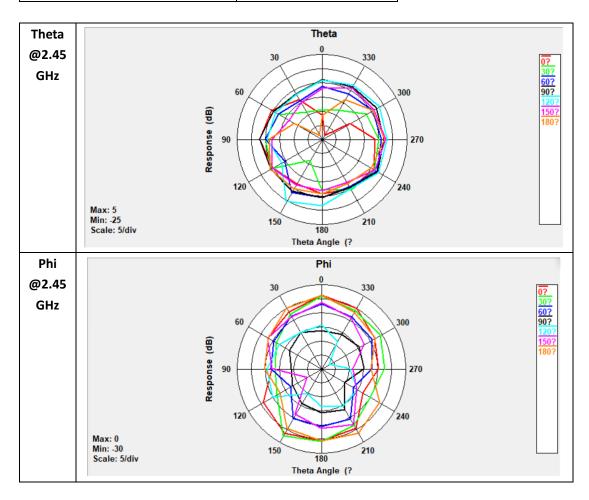


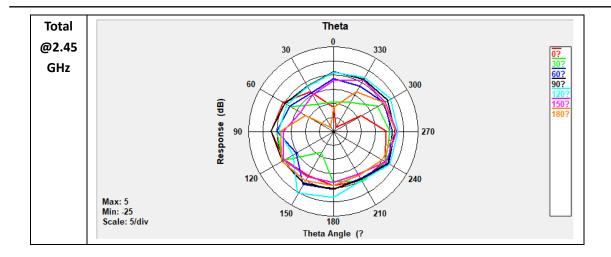
#### **Efficiency and RADIATION PATTERN**

Efficiency, Radiation Pattern and Gain were dependent on measurement board design. The specification of CA-C01 antenna was measured based on the PCB size and installation position as shown in the below figure test board. The test results were tested in ETS 3D Chamber.



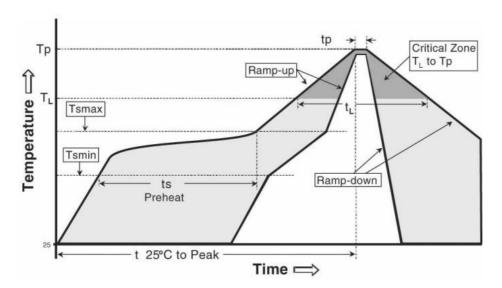
Gain and Efficiency	2.4G-2.5GHz		
Peak Gain	0.2dBi		
Average Gain across the band	0.06dBi		
Gain Range across the band	-0.17dBi~0.2dBi		
Peak Efficiency	41.3%		
Average Efficiency across the band	40.1%		
Efficiency Range across the band	37.8%~41.3%		





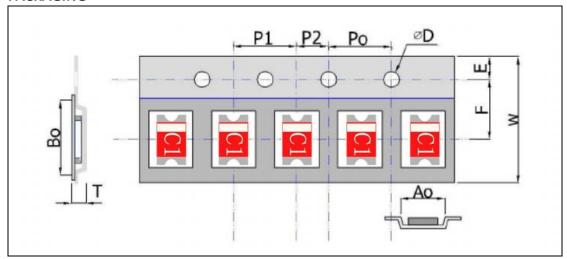
# **SOLDERING CONDITION**

Typical examples of soldering processes that provide reliable joints without any damage is as follows:



Phase	Profile features	Pb-Free assembly (SnAgCu)		
RAMP-UP	Avg. Ramp-up Rate (Tsmax to Tp)	3 °C / second (max.)		
PREHEAT	- Temperature Min (Tsmin) - Temperature Max (Tsmax) - Time (tsmin to tsmax)	150 °C 200 °C 60-180 seconds		
REFLOW	- Temperature (TL) - Total Time above TL (tL)	217 °C 60-150 seconds		
PEAK	- Temperature (Tp) - Time (tp)	260 °C 20-40 seconds		
RAMP-DOWN	Rate	6 °C/second max		
Time from 25 °C to Peak Temperature		8 minutes max		

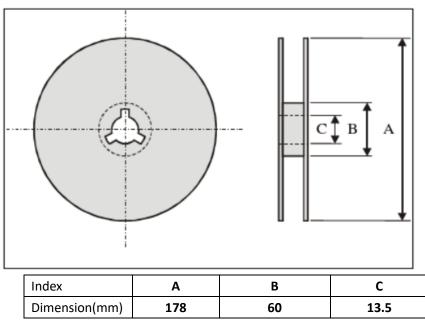
# **PACKAGING**



# Plastic Tape specification (unit:mm)

Index	Ao	Во	Фр	Т	W
Dimension (mm)	2.0±0.1	3.6±0.1	1.55±0.05	0.9±0.1	8.2±0.1
Index	E	F	Ро	P1	P2
Dimension (mm)	1.75±0.1	3.2±0.1	4.0±0.1	4.0±0.1	2.0±0.1

#### **Reel dimensions**



Typing Quantity: 3000 pieces per reel.

# **CAUTION OF HANDLING**

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# Storage environment condition

Products shoud be storage in the warehouse on the following conditions:

Temperature :  $-10^{\circ}$ C ~+40  $^{\circ}$ C

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Humidity : 30% to 70% relative humidity

Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.

Products should be storage on the palette for the prevention of the influence from humidity, dust and so on.

Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.

Products should be storage under the airtight packaged condition.